```
DIALOG(R) File 351: Derwent WPI
(c) 2005 Thomson Derwent. All rts. reserv.
012682822
WPI Acc No: 1999-488929/199941
 Thermoconductive silicone rubber composition - comprising silicone
 rubber(s), and thermoconductive inorganic filler(s) treated with silane
 coupling agent(s)
Patent Assignee: MATSUSHITA ELECTRIC WORKS LTD (MATW )
Number of Countries: 001 Number of Patents: 002
Patent Family:
                             Applicat No
                                            Kind
                                                   Date
             Kind
                     Date
Patent No
                                                 19980127 199941 B
            A 19990803 JP 9814565
                                            Α
JP 11209618
                                                 19980127 200241
              B2 20020610 JP 9814565
                                            Α
JP 3290127
Priority Applications (No Type Date): JP 9814565 A 19980127
Patent Details:
                                     Filing Notes
                         Main IPC
Patent No Kind Lan Pg
JP 11209618 A 10 C08L-083/04
                    11 C08L-083/04
                                     Previous Publ. patent JP 11209618
              B2
JP 3290127
Abstract (Basic): JP 11209618 A
        Thermoconductive silicone rubber composition (I) comprising (a) and
    (b) is claimed. (a) = silicone rubber(s); (b) = thermoconductive
    inorganic filler(s) treated with silane coupling agent(s) of formula
    YSiX3 (A) or Y2SiX2 (B); X= methoxy, ethoxy, and; Y= alkyl having 6 or
    more carbon atoms, phenyl.
        USE - (I) is useful as material for preparation of heat-radiating
    sheet(s) for electrical and electronic instruments.
        ADVANTAGE - (I) has good fluidity and thermal conductivity, and
    gives heat-radiating sheet(s) having good resistance to thermal aging.
        Dwg.0/2
Derwent Class: A26; A60; A85; L03; V04
International Patent Class (Main): CO8L-083/04
International Patent Class (Additional): C08K-007/04; C08K-009/06;
  H01L-023/36
```